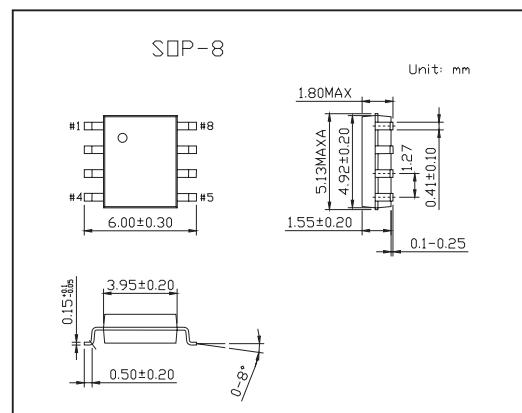
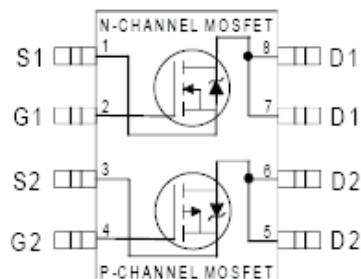


## HEXFET® Power MOSFET

### KRF7350

#### ■ Features

- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Available in Tape and Reel



#### ■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	-100	V
Continuous Drain Current Ta = 25°C	I <sub>D</sub>	2.1	-1.5	
Continuous Drain Current Ta = 70°C	I <sub>D</sub>	1.7	-1.2	A
Pulsed Drain Current *1	I <sub>DM</sub>	8.4	-6.0	
Power Dissipation @Ta= 25°C	P <sub>D</sub>	2.0		W
Linear Derating Factor		0.016		W/°C
Gate-to-Source Voltage	V <sub>Gs</sub>	±20		V
Single Pulse Avalanche Energy *4	E <sub>AS</sub>	35	51	mJ
Peak Diode Recovery dv/dt *2	dv/dt	4.0	4.3	V/ns
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to + 150		°C
Maximum Junction-to-Ambient *3	R <sub>θJA</sub>	62.5		°C/W
Junction-to-Drain Lead	R <sub>θJL</sub>	20		

\*1 Repetitive rating; pulse width limited by max. junction temperature.

\*2 Pulse width ≤ 400 μ s; duty cycle ≤ 2%.

\*3 Surface mounted on 1 in square Cu board

\*4 N channel: Starting T<sub>J</sub> = 25°C, L = 4.0mH, R<sub>G</sub> = 25 Ω, I<sub>AS</sub> = 4.2A

P channel: Starting T<sub>J</sub> = 25°C, L = 11mH, R<sub>G</sub> = 25 Ω, I<sub>AS</sub> = -3.0A

**KRF7350**

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons		Min	Typ	Max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	VGS = 0V, ID = 250 μ A	N-Ch	100			V	
		VGS = 0V, ID = -250 μ A	P-Ch	-100				
Breakdown Voltage Temp. Coefficient	△V(BR)DSS/ △TJ	ID = 1mA, Reference to 25°C	N-Ch	0.12			V/°C	
		ID = -1mA, Reference to 25°C	P-Ch	-0.11				
Static Drain-to-Source On-Resistance	RDS(on)	VGS = 10V, ID = 2.1A*1	N-Ch		0.21		Ω	
		VGS = -10V, ID = -1.5A*1	P-Ch		0.48			
Gate Threshold Voltage	VGS(th)	VDS = VGS, ID = 250 μ A	N-Ch	2.0	4.0		V	
		VDS = VGS, ID = -250 μ A	P-Ch	-2.0		-4.0		
Forward Transconductance	gfs	VDS = 50V, ID = 2.1A*1	N-Ch	2.4			S	
		VDS = -50V, ID = -1.5A*1	P-Ch	1.1				
Drain-to-Source Leakage Current	Idss	VDS = 100V, VGS = 0V	N-Ch		25		μ A	
		VDS = -100V, VGS = 0V	P-Ch		-25			
		VDS = 80V, VGS = 0V, TJ = 70°C	N-Ch		250			
		VDS = -80V, VGS = 0V, TJ = 70°C	P-Ch		-250			
Gate-to-Source Forward Leakage	Igss	VGS = ±20V	N-Ch		±100		nA	
			P-Ch		±100			
Total Gate Charge	Qg	N-Channel ID = 2.1A, VDS = 80V, VGS = 10V	N-Ch	19	28		nC	
Gate-to-Source Charge	Qgs		P-Ch	21	31			
Gate-to-Drain ("Miller") Charge	Qgd		N-Ch	3.0	4.5			
			P-Ch	3.4	5.1			
Turn-On Delay Time	td(on)	N-Channel VDD = 50V, ID = 1A, RG = 22 Ω P-Channel RD = 50 Ω, VGS = 10V	N-Ch	8.8	13		ns	
			P-Ch	10	16			
Rise Time	tr		N-Ch	6.7				
Turn-Off Delay Time	td(off)		P-Ch	25				
			N-Ch	11				
Fall Time	tf		P-Ch	13				
			N-Ch	35				
Input Capacitance	Ciss	N-Channel VGS = 0V, VDS = 25V, f = 1.0MHz P-Channel VGS = 0V, VDS = -25V, f = 1.0MHz	P-Ch	30			pF	
			N-Ch	20				
Output Capacitance	Coss		P-Ch	40				
			N-Ch	380				
Reverse Transfer Capacitance	Crss		P-Ch	360				
			N-Ch	100				
			P-Ch	110				
			N-Ch	54				
			P-Ch	65				

**KRF7350**

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons		Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	Is		N-Ch			1.8	A
			P-Ch			-1.4	
Pulsed Source Current (Body Diode) *2			N-Ch			8.4	
			P-Ch			-6.0	
Diode Forward Voltage	VSD	TJ = 25°C, Is = 1.8A, VGS = 0V*1	N-Ch			1.3	V
		TJ = 25°C, Is = -1.4A, VGS = 0V*1	P-Ch			-1.6	
Reverse Recovery Time	trr	N-Channel TJ = 25°C, IF = 1.8A, di/dt = 100A/ μ s*1	N-Ch		72	110	ns
		P-Channel TJ=25°C, IF=-1.4A, di/dt=-100A/ μ s*1	P-Ch		77	120	
Reverse RecoveryCharge	Qrr		N-Ch		205	310	nC
			P-Ch		240	360	

\*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

\*2 Repetitive rating; pulse width limited by max. junction temperature.